



seit 1558



Sebastian Döring

Friedrich-Schiller-University Jena

Thin film Josephson junctions for the characterization of iron-based superconductors

Trilateral workshop on Hot Topics in HTSC

29.Sep.-02.Okt.2013

DFG

SPP 1458



Outline

- Tasks
- Junction preparation
- Results of planar junctions
 - Au barrier
 - TiO_x barrier
- Results of edge-type junctions
- Junctions on single crystals
- Summary
- Outlook

- Deposition of the high-quality thin films of $\text{Ba}(\text{Fe}_{1-x}\text{Co}_x)_2\text{As}_2$ at IFW Dresden
substrates: STO, LSAT, MgO, CaF_2
- Co-doped Ba-122 single crystals at KIT Karlsruhe
- Preparation of junctions
- Investigation of superconducting properties
 - Critical current density
 - Order parameter
- Tuning of junction properties
 - $I_c R_n$ product
 - Barrier transparency



Preparation

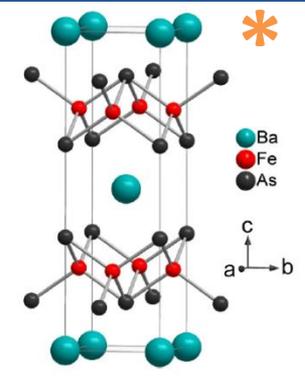
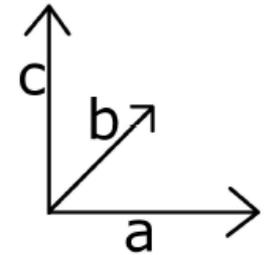
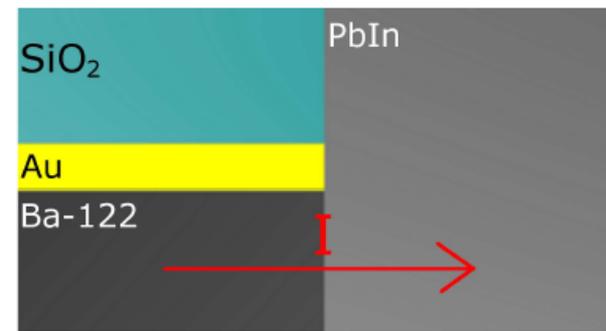
Junction types

Thin film Josephson junctions

S. Döring
(FSU Jena)

planar SXS'-junction

edge-type junction



current direction	c-axis	ab-plane
barrier	Au layer (5...10nm) Au+TiO _x (1...3nm)	Interface engineered (ion beam, chemicals, air)

*

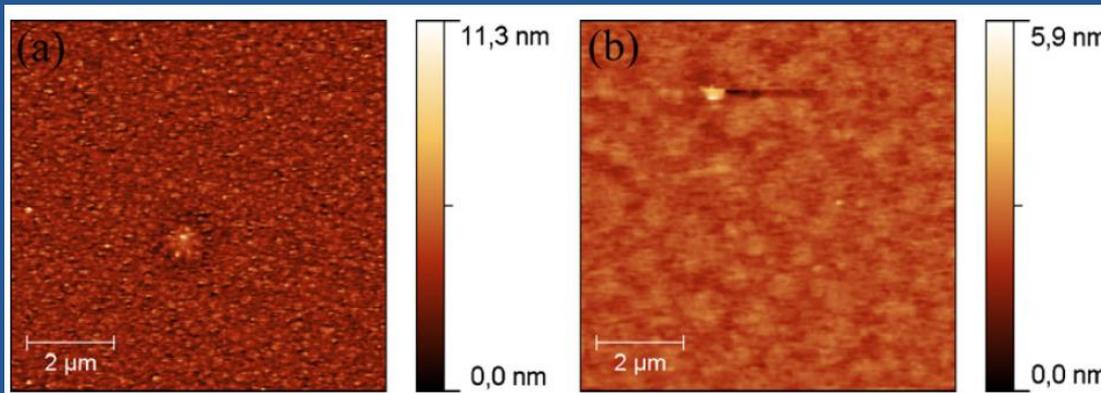
Rotter et al. *Phys. Rev. Lett.* **101** (2008) 107006

Preparation

Process steps

Thin film Josephson junctions
S. Döring
(FSU Jena)

	planar SNS-junction	edge-type junction
		
Process(es):	IB, SiO ₂ sputter, EBL, photo, etching, photo, etching, photo, etching, photo, etching	IB, SiO ₂ sputter, EBL, photo, etching, photo, etching, photo, etching, photo, etching
	Lift-off	Lift-off
Affected part:	Insulation layer, Superconductor	Insulation layer



Döring et al. *Physica C* **478**
(2012) 15-18

Preparation

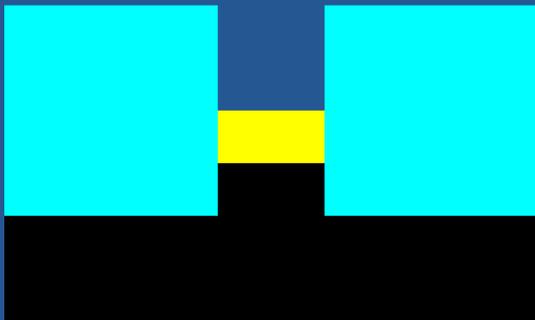
Titanium oxide barriers

Thin film Josephson junctions

S. Döring
(FSU Jena)

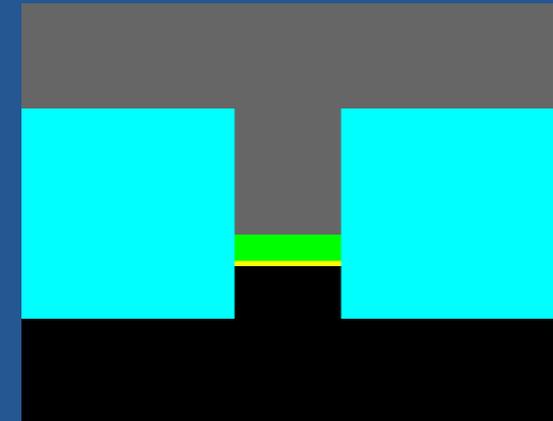
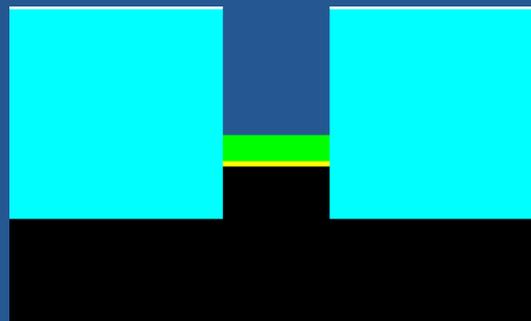
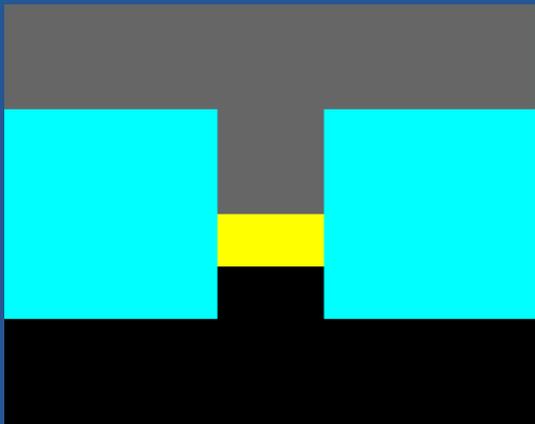
Preparation of planar junctions

previously



Döring et al. arXiv.org 1309.2331
Submitted to Appl. Phys. Lett.

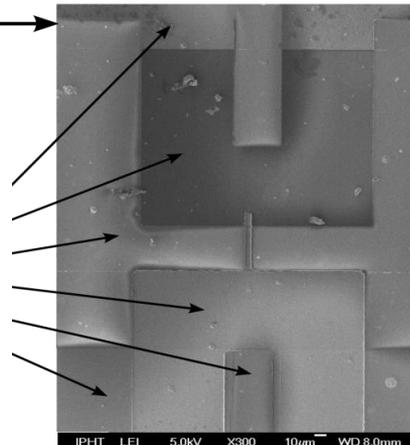
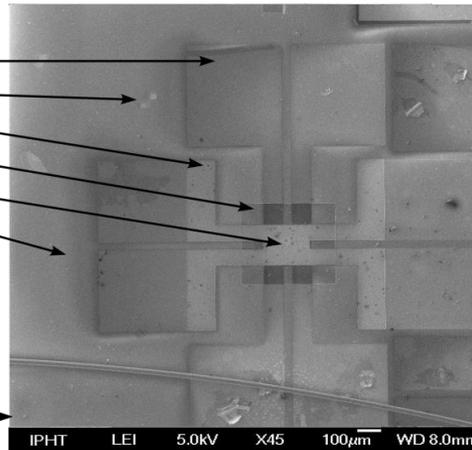
- Patterning junction area by SiO₂ framework
- Evaporating (6.5g Pb) on the gold layer as electrode
- Sputtering Ti (1..3nm)
- Heating and oxidation in atmosphere
- Evaporating Pb and In as counter electrode



Preparation

Overview

base electrode (Ba-122, Au-covered)
marker
counter electrode (Pb, In-covered)
junction framework (SiO₂)
junction area
substrate (MgO)



base electrode (Ba-122, Au-covered)
Base electrode (SiO₂-covered)
SiO₂ insulation layer
counter electrode (Pb, In-covered)
substrate (MgO)
bonding pads (Ba-122, Au-covered)

Single sample:

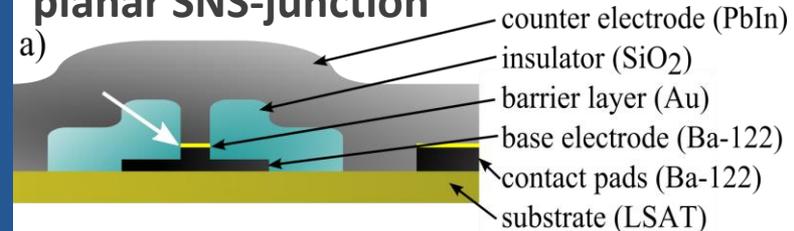
- 5mm x 10mm
- 10 planar junctions
- 5 edge junctions

Junction areas:

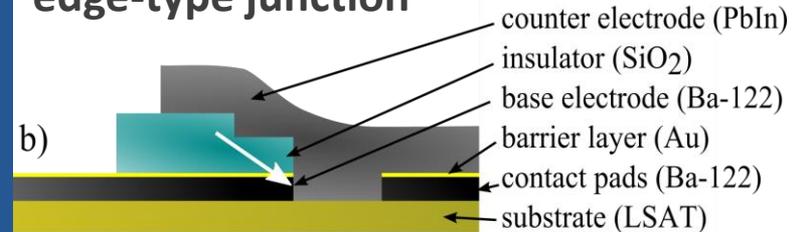
Planar: 3x3...100x100 μm²

Edge-type: 3...20μm x film thickness

planar SNS-junction



edge-type junction



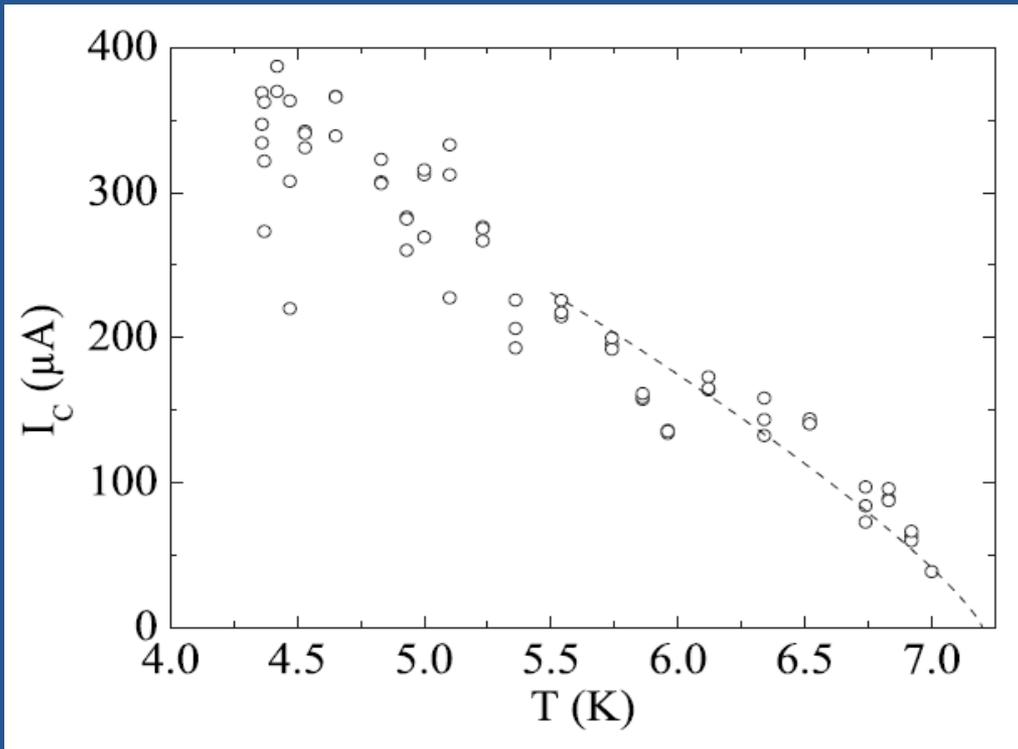
Results on planar junctions

Junctions with Au barrier

Thin film Josephson
junctions

S. Döring
(FSU Jena)

planar SNS-junction (5nm Au)



I-V-characteristic:

Asymmetric shape

- $I_c \approx 350 \mu\text{A}$
- $R_n = 53 \text{m}\Omega$
- $I_{ex} \approx 200 \mu\text{A}$
- $I_c R_n = 18 \mu\text{V}$, corr: $I_c R_n = 7.9 \mu\text{V}$

$I_c - T$ dependence:

- nearly linear

Schmidt et al. *Appl. Phys. Lett.* **97**
(2010) 172504

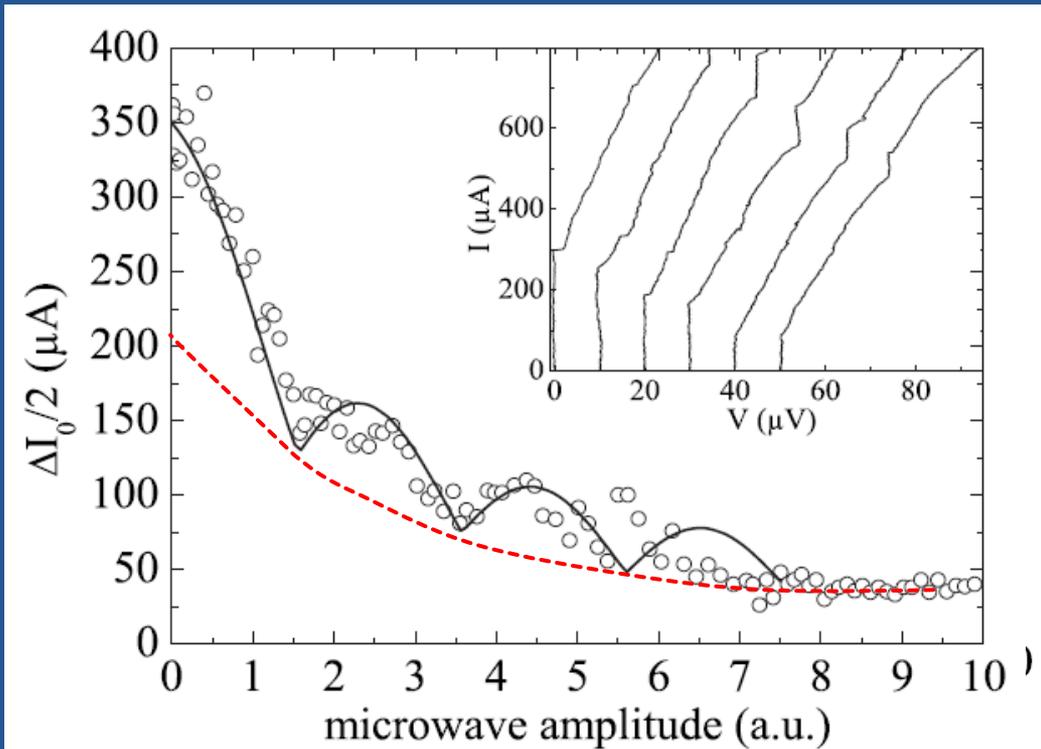
Results on planar junctions

Junctions with Au barrier

Thin film Josephson junctions

S. Döring
(FSU Jena)

planar SNS-junction (5nm Au)



Shapiro steps
 $n=2eV/hf$

Microwave dependence (12GHz):

- Bessel behavior
- Exponential underground
- Offset $\approx 30\mu\text{A}$

Schmidt et al. *Appl. Phys. Lett.* **97**
(2010) 172504

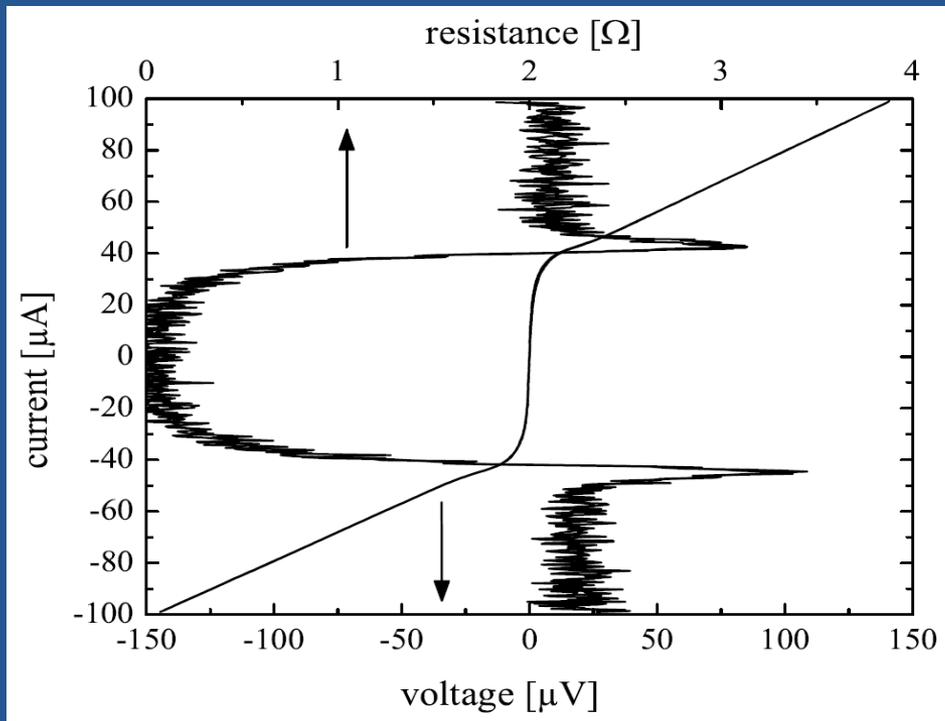
Results on planar junctions

Junctions with TiO_x barrier

Thin film Josephson
junctions

S. Döring
(FSU Jena)

Planar junction (1.5nm TiO_x)



- Symmetric I-V-characteristic
- RSJ + Flux Flow
- $I_c \approx 40 \mu\text{A}$
- $R_n = 2.2 \Omega$
- $I_c R_n \approx 90 \mu\text{V}$
- \Rightarrow increase by factor 5

Döring et al. [arXiv.org 1309.2331](https://arxiv.org/abs/1309.2331)

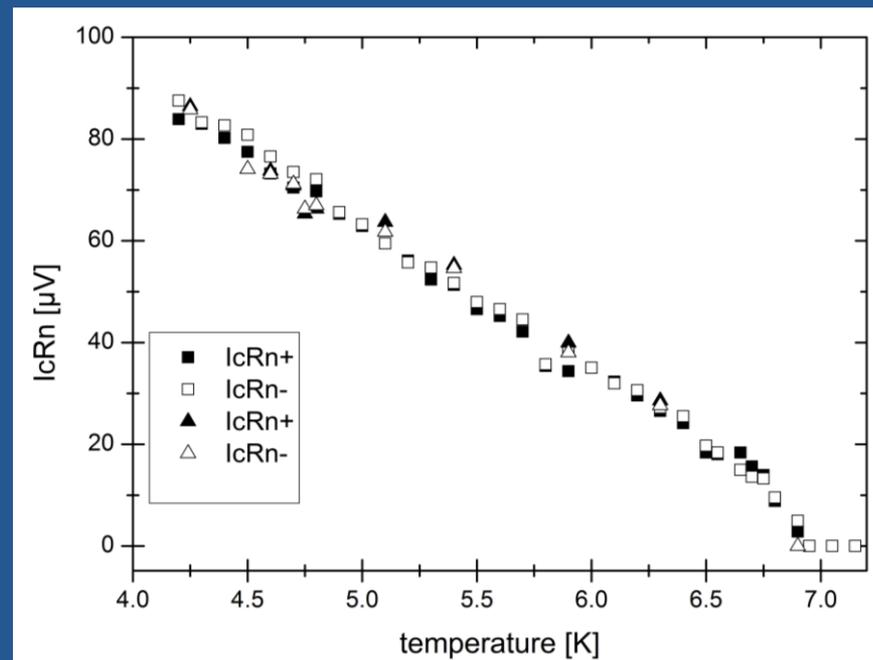
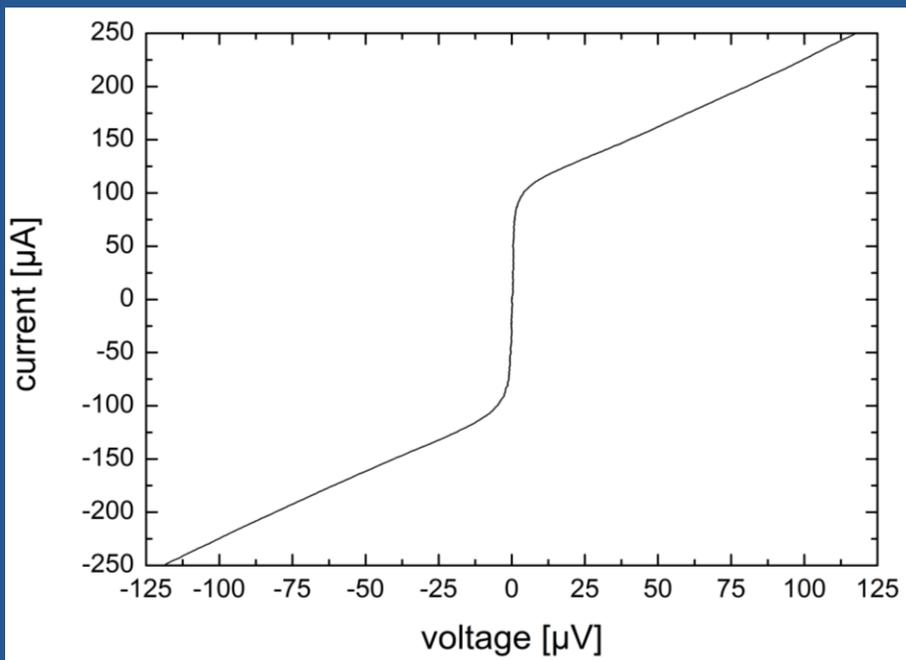
Results on planar junctions

Junctions with TiO_x barrier

Thin film Josephson junctions

S. Döring
(FSU Jena)

Planar junction (2.0nm TiO_x)



Results on planar junctions

Junctions with TiO_x barrier

Thin film Josephson junctions

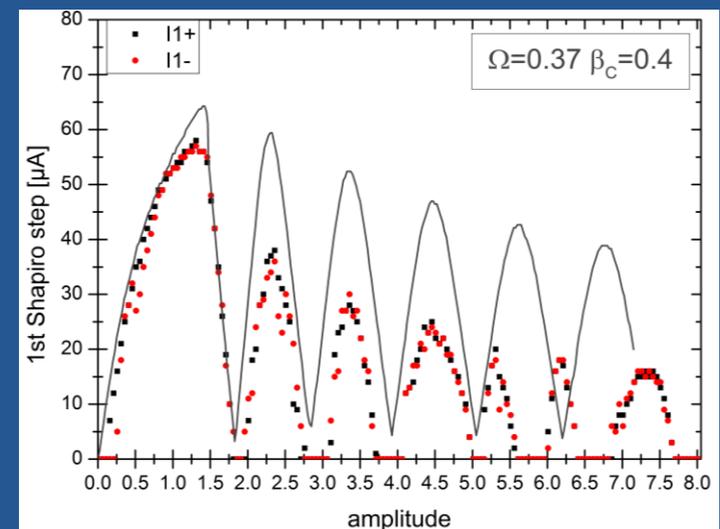
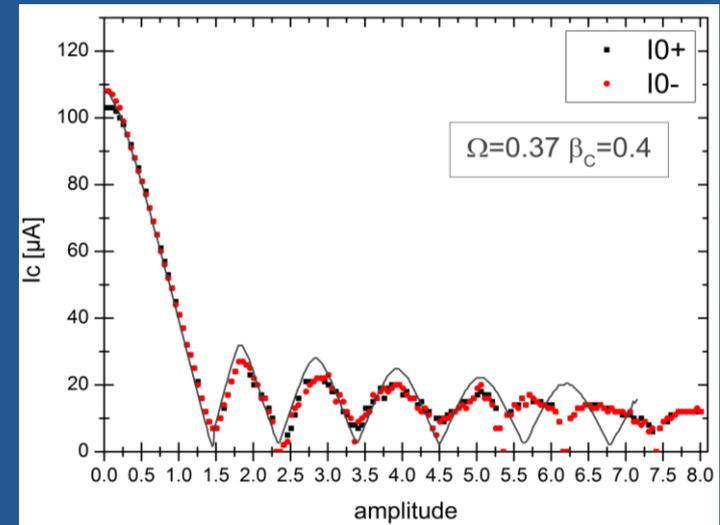
S. Döring
(FSU Jena)

Planar junction (2.0nm TiO_x)

$$\beta_C \ddot{\varphi} + \dot{\varphi} + \sin \varphi = i_b + i_m \sin \Omega \tau$$

Microwave dependence:

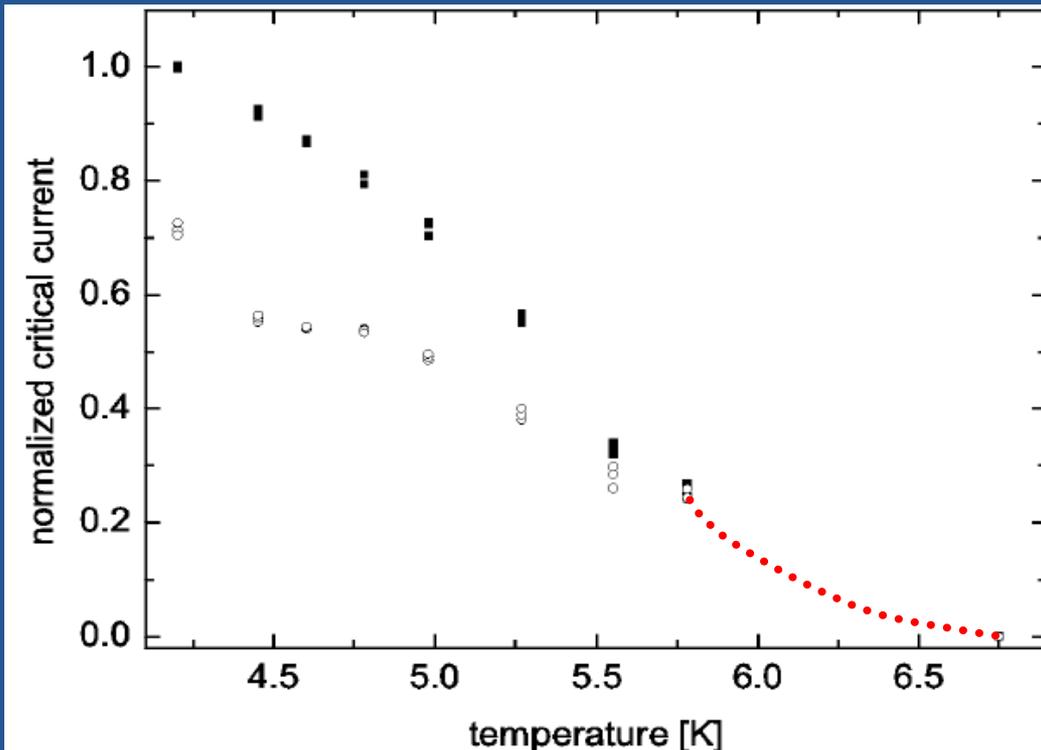
- Fitable within simple Josephson equation
- No background needed
- Good periodicity



Results on edge-type junctions

Thin film Josephson junctions
S. Döring
(FSU Jena)

Edge-type junction



I-V-characteristic:
Asymmetric shape

Parameter	positive	negative
I_c	59 μ A	42 μ A
R_n	217m Ω	197m Ω
I_{ex}	24 μ A	22 μ A
$I_c R_n$	12.7 μ V	8.2 μ V
$I_c R_n$ (corr.)	7.7 μ V	3.9 μ V

$I_c - T$ dependence

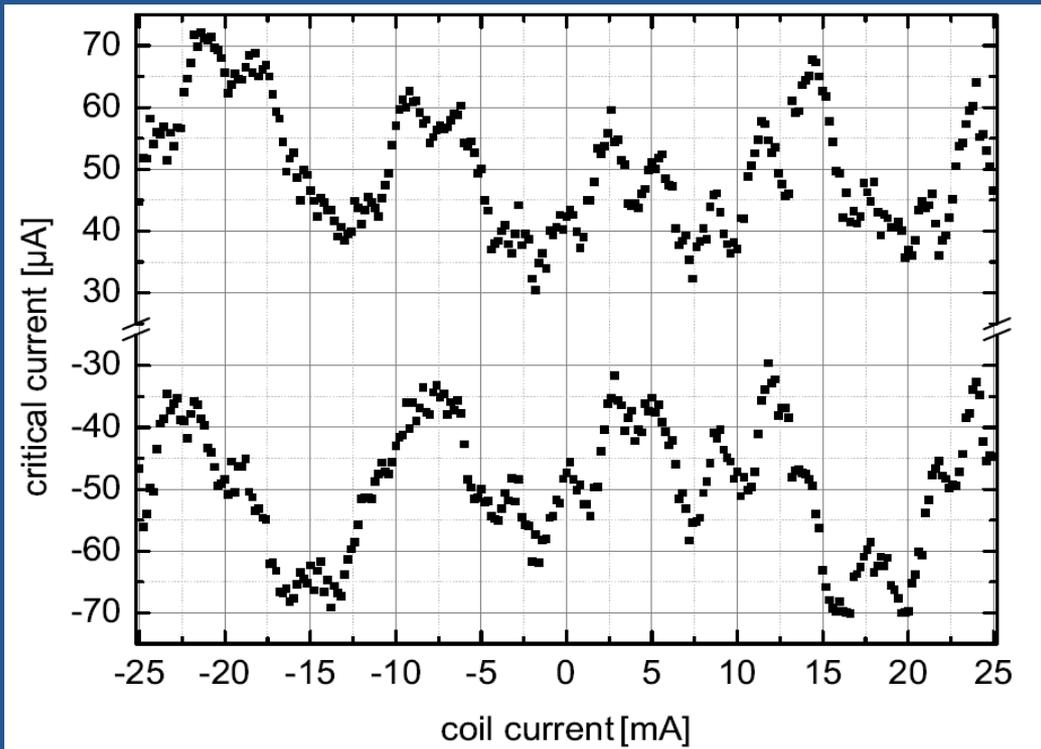
- Asymmetric but uncertain near T_c

Döring et al. *Supercond. Sci. Technol.* 25 (2012), 084020

Results on ede-type junctions

Thin film Josephson junctions
S. Döring
(FSU Jena)

Edge-type junction



Shapiro steps

Microwave dependence (6GHz):

- Uncertain
- No offset

Magnetic field dependence:

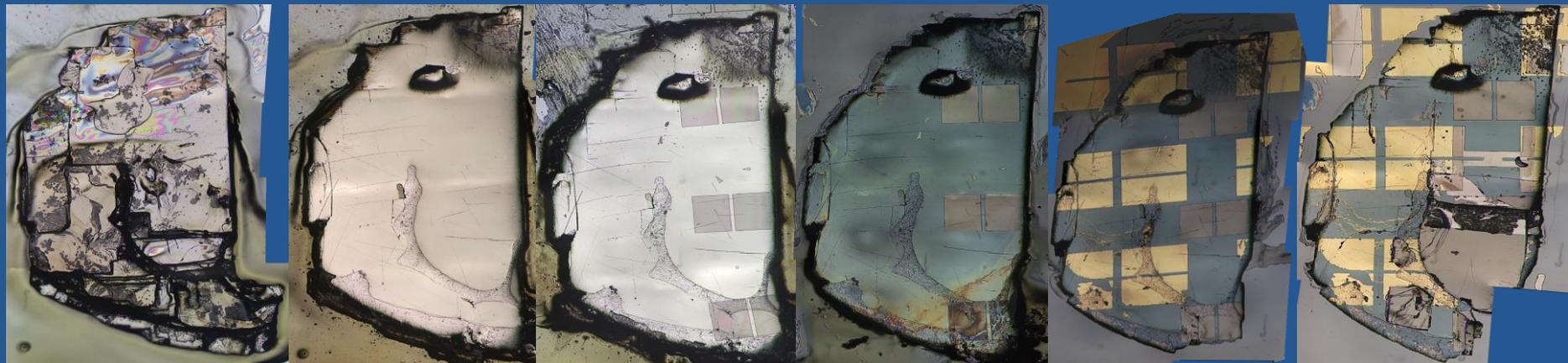
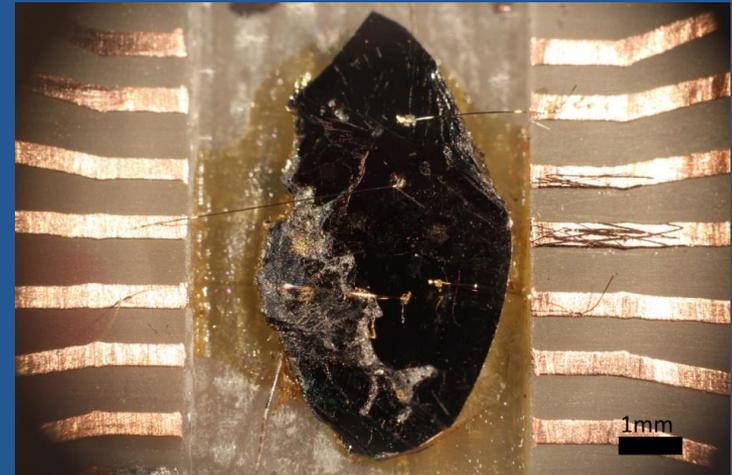
- Countercyclical behavior
- Offset: $30\mu\text{A}$
- No suppression of I_c

Döring et al. *Supercond. Sci. Technol.* **25** (2012), 084020

Single crystals

Thin film Josephson
junctions
S. Döring
(FSU Jena)

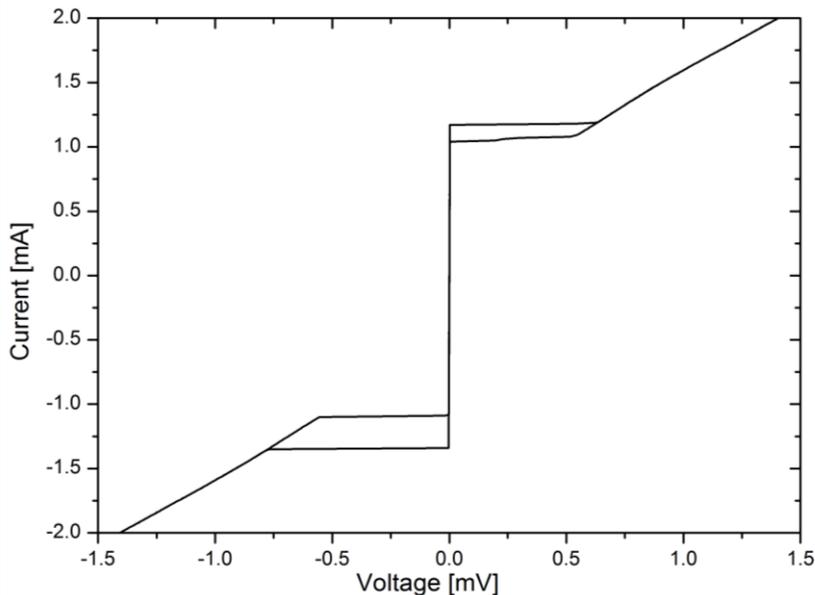
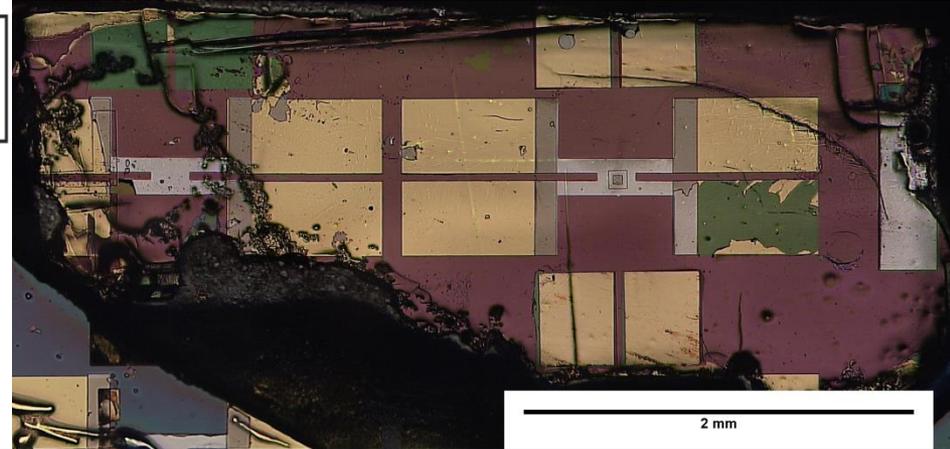
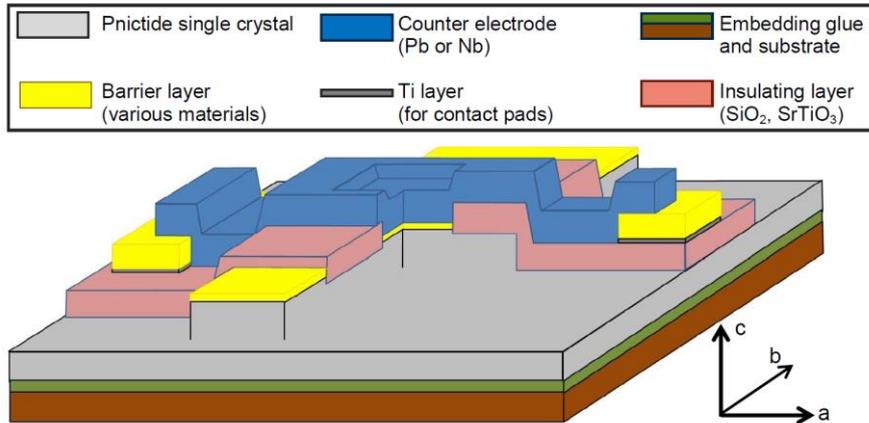
- Junction designs are transferable to single crystals
- Additional competitions:
 - Embedding (Epoxy glue)
 - Polishing (RMS<2nm)
 - Insulation (SiO₂ d=400nm)



Single crystals

Thin film Josephson junctions

S. Döring
(FSU Jena)



Planar junction with 2.5nm TiO_x barrier:

$I_c = 1.2 \text{ mA}$

$R_n = 1 \Omega$

$I_c R_n = 1.2 \text{ mV}$

Hysteretic I-V characteristic:

Insulating barrier

$\beta_c > 1$

- Preparation of planar and edge-type junctions from Ba-122 thin films
- Josephson effect observed for both types
- Problems with Au barriers and edge-types
- TiOx barriers:
 - Increase of $I_c R_n$
 - Avoid of disturbing effects
- Successful transfer to single crystals

- Real tunneling (SIS) junctions
- Controlling and tuning the properties of edge-type junctions
- Explanation of low $I_c R_n$ products
- Combination of junctions for phase-sensitive test

Спасибо за ваше внимание!

Дякуємо за вашу увагу!

Vielen Dank für ihre Aufmerksamkeit!

Thanks to:

KIT Karlsruhe	IFW Dresden:	FSU Jena:
Dr. Thomas Wolf	Fritz Kurth	Stefan Schmidt
	Jan Engelmann	Manuel Monecke
	Dr. Kazumasa Iida	David Reifert
	Dr. Silvia Haindl	Noor Ali Hasan
	Dr. Ingolf Mönch	Dr. Volker Tympel
	Prof. Dr. Bernhard Holzapfel	Prof. Dr. Frank Schmidl
		Prof. Dr. Paul Seidel